What Is Claimed Is:

1. A method for manufacturing electronic parts comprising:

a conveying step wherein plate-form electronic parts sealed in resin are conveyed;

a first fastening step wherein conveyed said plate-form electronic parts are positioned and fastened in place;

a first cutting step wherein said plate-form electronic parts that have been positioned and fastened in place in said first fastening step are moved in one direction on the plane that includes said plate-form electronic parts, and are cut;

a second fastening step wherein rectangular-form electronic parts that have been cut in said first cutting step are conveyed, positioned and fastened in place;

a second cutting step wherein said rectangular-form electronic parts that have been conveyed, positioned and fastened in place in said second fastening step are moved in a direction that crosses the abovementioned cutting direction, and are cut; and

a product accommodating step wherein single electronic parts that have been cut in said second cutting step are accommodated.

2. The method for manufacturing electronic parts according to claim 1, wherein said first fastening step and said second

fastening step include a position recognition step wherein the positions of said rectangular-form electronic parts or said rectangular-form electronic parts that have been conveyed are optically recognized.

3. The method for manufacturing electronic parts according to claim 1 or claim 2, wherein said first fastening step and said second fastening step are press-fastening steps wherein said plate-form electronic parts or said rectangular-form electronic parts are fastened in place by the application of pressure from above after said electronic parts have been placed on a carrying table.

4. The method for manufacturing electronic parts according to claim 1 or claim 2, wherein said first cutting step and said second cutting step are steps wherein cutting is performed by causing a rotary abrasive wheel to move.

5. The method for manufacturing electronic parts according to claim 1 or claim 2, wherein said first cutting step and said second cutting step include a step wherein dust or the like generated by cutting is removed by suction.

6. The method for manufacturing electronic parts according to claim 1 or claim 2, wherein said product accommodating step includes a step wherein said single electronic parts cut in said second cutting step are clamped and inverted, and the orientation of said single electronic parts is altered.

7. The method for manufacturing electronic parts according to claim 1 or claim 2, wherein said product accommodating step includes a step wherein clamped said single electronic parts are brushed.

8. An apparatus for manufacturing electronic parts comprising:

a conveying body which is used to convey a plate-form electronic parts;

a first fastening device which positions and fastens plate-form electronic parts sealed in resin that are conveyed by said conveying body;

a first cutting device which moves said plate-form electronic parts that have been positioned and fastened in place by said first fastening device in one direction on the plane that includes said plate-form electronic parts, and cuts said plate-form electronic parts;

a second fastening device which conveys, positions and fastens rectangular-form electronic parts that have been cut by said first cutting device;

a second cutting device which moves said rectangular-form electronic parts that have been conveyed, positioned and fastened in place by said second fastening device in a direction that crosses the abovementioned cutting direction, and which cuts said rectangular-form electronic parts; and

a product accommodating device which accommodates the single electronic parts that have been cut by said second cutting device.

9. The apparatus for manufacturing electronic parts according to claim 8, wherein said first fastening device and said second fastening device contain a position recognition device which optically recognizes the positions of said plate-form electronic parts or said rectangular-form electronic parts that have been conveyed.

10. The apparatus for manufacturing electronic parts according to claim 9, wherein the device that optically recognizes the positions of said plate-form electronic parts or said rectangular-form electronic parts is a device which recognizes the

shapes of said plate-form electronic parts or said rectangular-form electronic parts by means of a CCD camera, and specifies the cutting positions.

11. The apparatus for manufacturing electronic parts according to claim 8, wherein said first fastening device and said second fastening device are devices that fasten said conveyed plate-form electronic parts or said rectangular-form electronic parts by means of restraining members that apply pressure from above after the electronic parts have been placed on a carrying table.

12. The apparatus for manufacturing electronic parts according to claim 11, wherein said first pressure-applying fastening device and said second fastening device are additionally provided with means for fastening said rectangular-form electronic parts or said rectangular-form electronic parts by means of a vacuum suction force.

13. The apparatus for manufacturing electronic parts according to claim 11, wherein in said first pressure-applying fastening device and said second fastening device, projecting parts which are used to press said plate-form electronic parts or

said rectangular-form electronic parts are disposed on said restraining members.

14. The apparatus for manufacturing electronic parts according to Claim 11, wherein the restraining members which fasten said plate-form electronic parts or said rectangular-form electronic parts after said electronic parts have been placed on a carrying table have cutting grooves formed in said carrying table and said restraining members, which are used to allow the passage of a rotary tool in order to cut said plate form electronic parts and said rectanglar-form electronic parts.

15. The apparatus for manufacturing electronic parts according to claim 8, wherein said first cutting device and said second cutting device are equipped with dust collectors that use suction to capture the dust-form cutting debris that is generated by cutting.

16. The apparatus for manufacturing electronic parts according to claim 8, wherein said first cutting device and said second cutting device are devices which have rotary cutting tools, and which perform advancing and retracting movements on two or more axes.

17. The apparatus for manufacturing electronic parts according to claim 16, wherein said rotary cutting tools are tools that are formed as composite tools by the electrodeposition of diamond abrasive grains and CBN abrasive grains.

18. The apparatus for manufacturing electronic parts according to claim 8, wherein said product accommodating device is a device which clamps the single electronic parts cut by said second cutting device, inverts said electronic parts and alters the orientation of said electronic parts.

19. The apparatus for manufacturing electronic parts according to claim 8, wherein said product accommodating device is a device which brushes clamped said single electronic parts.